



RELIABILITY REPORT
FOR
MAX16008TP+
PLASTIC ENCAPSULATED DEVICES

October 15, 2010

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.
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Approved by
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Conclusion

The MAX16008TP+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX16008/MAX16009 are adjustable quad window voltage detectors in a small thin QFN package. These devices are designed to provide a higher level of system reliability by monitoring multiple supply voltages and providing a fault signal when any of the voltages exceed their overvoltage thresholds or fall below their undervoltage thresholds. These devices offer user-adjustable thresholds that allow voltages to be monitored down to 0.4V. These devices allow the upper and lower trip thresholds of each window detector to be set externally with the use of three external resistors. Each monitored threshold has an independent open-drain output for signaling a fault condition. The outputs can be wired OR'd together to provide a single fault output. The open-drain outputs are internally pulled up with a 30 μ A current, but can be externally driven to other voltage levels for interfacing to other logic levels. Both devices feature a margin enable input to disable the outputs during margin testing or any other time after power-up operations. The MAX16009 offers a reset output that deasserts after a reset timeout period after all voltages are within their threshold specifications. The reset timeout is internally set to 140ms (min), but can be externally adjusted to other reset timeouts using an external capacitor. In addition, the MAX16009 offers a manual reset input. All devices are offered in a 4mm x 4mm thin QFN package and are fully specified from -40°C to +125°C.

II. Manufacturing Information

A. Description/Function:	Low-Voltage, High-Accuracy, Quad Window Monitor in Small TQFN Package
B. Process:	B8
C. Number of Device Transistors:	3416
D. Fabrication Location:	California or Texas
E. Assembly Location:	China, Thailand
F. Date of Initial Production:	October 22, 2005

III. Packaging Information

A. Package Type:	20-pin TQFN 4x4
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-2031
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	59°C/W
K. Single Layer Theta Jc:	5.7°C/W
L. Multi Layer Theta Ja:	39°C/W
M. Multi Layer Theta Jc:	5.7°C/W

IV. Die Information

A. Dimensions:	78 X 79 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 45 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 24.4 \times 10^{-9}$$

$\lambda = 24.4$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the B8 Process results in a FIT Rate of 0.06 @ 25C and 0.99 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot TZB0AQ001G, D/C 0538)

The MS96-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX16008TP+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	45	0	TZB0AQ001L, DC 0533

Note 1: Life Test Data may represent plastic DIP qualification lots.